N4906A-01

SERVICE NOTE

Supersedes: NONE

N4906A 3Gb/s SerialBERT

Serial Numbers: [0000A00000 / 9999Z99999]

Incorrect frequency or high jitter when using internal clock source may require replacement of Pattern Generator Clock Path Assembly.

To Be Performed By: Agilent-Qualified Personnel

Parts Required:

P/N Description Qty.

86130-69002 Clock Path Bd – Refurbished 1

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION:		
MODIFICATION RECOMMENDED		
ACTION CATEGORY:	[[]] IMMEDIATELY X ON SPECIFIED FAILURE [[]] AGREEABLE TIME	STANDARDS: LABOR: 1.0 Hours + CAL
LOCATION CATEGORY:	[[]] CUSTOMER INSTALLABLE [[]] ON-SITE X SERVICE CENTER	SERVICE X RETURN USED X RETURN INVENTORY: [[]] SCRAP [[]] SEE TEXT [[]] SEE TEXT
AVAILABILITY:	PRODUCT'S SUPPORT LIFE	AGILENT RESPONSIBLE UNTIL: 26 Jan 2007
AUTHOR: RBS ADDITIONAL INFORM	PRODUCT LINE: 8F	

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Situation:

The A2A1 Clock Path Assembly may require replacement to resolve data and clock amplifier output performance degradation when using the internal clock source (synthesizer). A defective A2A1 assembly may cause excessive jitter on the data amplifiers, or may result in a doubling of the output frequency (e.g. set 1.0GHz, and displayed frequency is 2.0GHz).

This problem is ONLY evident when using the internal clock source since the prescalar/divider IC (U2, P/N 1GC1-4210) on A2A1 is bypassed when using an external clock source.

Elevated operating temperatures such as those found at the top of equipment racks can accelerate the time to failure of the IC (U2) (N4906A Operating Specification 10C-45C).

Solution/Action:

- 1. Confirm the instrument behavior is due to a defective A2A1 assembly.
 - a. Problem is NEVER evident when using external clock source.
 - b. Frequency doubling problem goes away when using internal clock source above 1.5GHz
- 2. Once confirmed, replace A2A1 (Clock Path Assy) and re-calibrate A2 (Pattern Generator) assembly.

NOTE: A2A1 U2 (1GC1-4210) is reworked in the factory. It requires special soldering techniques to ensure good ground-plane bonding on the IC underside.